

An Off-line Task Mapping Method based on Microring Perception Thermal Balance

Xiaoyu Guan, Ning Wu, Fen Ge, and Gaizhen Yan

Abstract—Photonic network-on-chip (PNoC) has emerged as a feasible solution for new multi core processor systems to avoid the limitations of power and bandwidth density of traditional electrical networks. However, it is inevitable that the photonic devices have high sensitivity to the temperature such as microring resonator which is widely used on NoCs. As the temperature is increased or decreased, wavelength shift is generated. In order to resolve that problem, an off-line task mapping based on the microring thermal perception is proposed in this paper. This scheme maps the tasks having high power consumption to the peripheral core before the application is executed, while the low power tasks are mapped first to the core of the light node that significantly decrease temperature of the optical node. The simulation results show that in a group of practical applications compared with the method based on shortest path mapping and our proposed scheme in $8 \times 8 \times 2$ three-dimensional mesh optical NoC, later mapping algorithm significantly reduce temperature of the optical node from 1K to 2K.

Index Terms—task mapping, microring perception, PNoC, thermal balance

I. INTRODUCTION

With the increasing limitations of transistors that can be integrated in a single-core chip, the proposed multi-core processor helps achieve high-performance parallel processing with lower frequency costs. The network-on-chip (NoC) is now recognized as emerging on-chip communication architecture proposed by the industry in place of traditional multi-core processors [1]. However, the on-chip network of electrical interconnects has obvious drawbacks in communication bandwidth and power consumption and if the chip structure is to be passed through a pure optical network, it also affects the stability of the

overall communications. Therefore, an optical networks-on-chip communication architecture is proposed. Compared with the traditional pure electrical interconnect architecture, optical networks-on-chip can significantly increase the bandwidth density, which provide low power consumption and communication delay.

The optical-electrical interconnect technology helps to build a low-diameter interconnect network that reduces the difference in access delays of on-chip nodes and reduces communication power of many-core systems [6-10]. Based on wavelength division multiplexing, the existing optical-electrical interconnect technology is mainly divided into two categories: circuit-switched and optical on-chip network. Circuit switched network needs to control the signal steering in the optical router through the parallel electronic control network, so that resource utilization rate of the network is reduced and the communication speed of the optical link is also limited. Only when the amount of transmitted data is in the order of 1 KB or more in this way, the extra overhead caused by link establishment and release can be offset. An on-chip optical network on account of wavelength division multiplexing uses a passive optical switch to route according to the wavelength of optical information. Optical signals can be transmitted without the need for optical signals or optical signal buffers. For resource reservation requirements, the intermediate nodes are eliminated from the light, which can make better use of the advantages of high-speed and low loss optical interconnection. In addition, the resource reservation has become a popular trend in optical network research.

The thermal sensitivity of the optical link is a problem that needs to be resolved in optical networks based on wavelength division multiplexing technology. The thermal stability control of optical link is mainly reflected in temperature control of the microring resonator. The microring resonator is a basic component of an optical link, which provides signal modulation at transmitter, light deflection during transmission and optical filtering at receiver end. However, microring resonators are very sensitive to temperature fluctuations (thermal temperature coefficient is about 110pm/K), that make optical links such as optical modulation, optical deflection and optical filtering malfunction, when the on-chip temperature changes. Some literatures have evaluated the thermal stability of 2D on-chip optical network through experimental methods. Without any thermal management measures average communication error rate of the entire network is more than 10^{-1} . In order to reduce the thermal effects in optical NoC, many thermal management techniques have been proposed such as OS-based workload migration and DVFS (Dynamic Voltage

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and Frequency Scaling) to reduce the on-chip temperature gradient. In addition, microring resonators and athermal microring resonators with small temperature dependence can be made by thermal properties of the polymer materials. However, this scheme has more requirements on the process. In addition, some efforts have been made to overcome thermal challenges in optical NoCs at a system level perspective. Author proposed a thermal sensing method to design an optical NoCs with distributed CMOS-compatible VCSELs (vertical cavity surface-emitting lasers) through analysis in [16]. Simulation of thermal effects in optical NoCs and several low-temperature sensitive technologies are proposed in [14], [15]. A system-level active thread migration technology and a device-level heat island framework to alleviate the thermal problem in optical NoC is published in [17].

Thermal compensation using a heating loop and a closed-loop control circuit is a mature thermal stability control method in industry. The resulting power consumption is called thermal tuning power consumption. Since the heating ring cannot dissipate heat, whether the microring is red-shifted or blue-shifted requires a heating operation. When the thermally stable operating range is 20K, the tuning power consumption of a single microring can reach 20μW. That makes the interconnection system available to receive constraints and increase power consumption overhead. In fact, the microrings in same optical node have similar temperature loop mirrors and same temperature characteristics. Therefore, the offline task mapping temperature control scheme is used to uniformly tune all the microrings at the same optical node to avoid additional heating loop temperature tuning power.

II. THERMAL-SENSITIVE DESIGN AND TASK MAPPING ALGORITHM REVIEW STAGE

In this section, the heat-sensitive characteristics of the microring resonator and the effects of temperature changes on the wavelength are analyzed. Based on optical thermal model, thermal effect in optical NoCs is described from a system level perspective. Moreover, an off-line task mapping algorithm based on thermal sensitivity for real applications is proposed for 3D mesh optical NoCs.

A. 3D mesh-based optical NoC architecture

Compared with electrical NoCs, photonic NoCs is a new technology as it has low power consumption and higher bandwidth. So far, the industry has proposed several high performance PNoC topologies, such as mesh [2], [4], 3D-mesh [5] [11], crossbar [3], torus [12] and clos [13]. Our main focus is on MRR's and waveguides.

As shown in Fig. 1, the routing structure of PNoC is a 5×5 optical router. One of the router ports is connected to the core while the other four ports are connected to the neighboring routers. The key device in the router is MRR(microring resonator). MRR is an annular coil waveguide which controls the propagation of optical signals. It is used as a basic switching element in photonic routers.

The switching mechanism of MRR is shown in Fig. 2. As shown in Fig. 2a and Fig. 2c, MRR allows optical signals to be transmitted straight through the input port without any

offsets in the closed state. When in open state (Fig. 2b and Fig.2d), MRR couples the optical signal of the waveguide wavelength from the waveguide A to the waveguide B. For reverse handover, two parallel waveguides are shown in Fig. 2b. As shown in Fig. 2d, the two waveguides are placed into rectangular switches with a 90 degree angle.

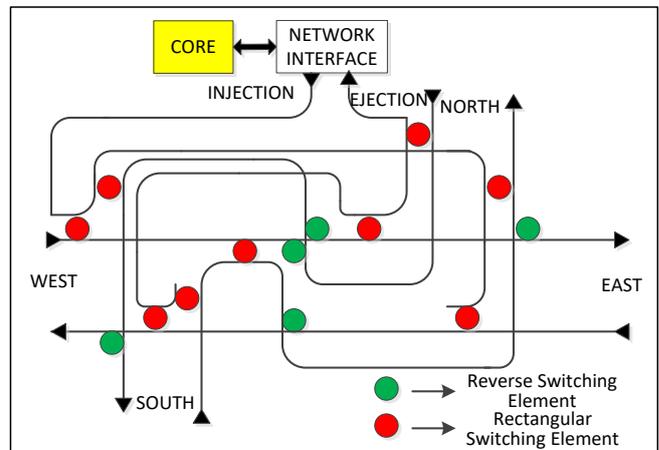


Fig. 1. Logical layout of router

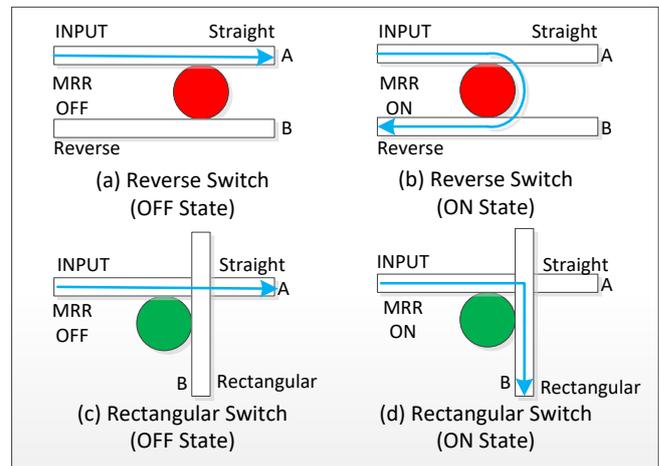


Fig. 2. MRR Switching

Optical NoCs transmit data and control information between processor core and memory through optical signal. In different Optical NoCs architectures, optical signals are transmitted through different optical links. Although the structure is diverse, the optical links in Optical NoCs are usually made up of optical paths, optical transmitters and optical receivers (shown on Fig. 3). The laser source can convert electrical signals into optical signals by directly modulating the driving current of VCSEL [29] or using optical modulators. VCSEL is assumed as the source of the PNoC laser and use 3D integration technology to connect the underlying CMOS drive circuit through VCSEL through TSVs (through silicon via).

Because NoC is designed to be predictable and scalable in terms of power and performance, traditional network topology such as grid and torus is the first choice. In order to improve the short connection characteristics of NoC, a NoC structure [18-20] is proposed based on 3D network topology. Compared with 2D implementation, it has been proved that NoC based on 3D grid can significantly increase the density of integration and the overall area will be smaller. In this paper NoC structure under the 3D-meshtopology is mainly

studied.

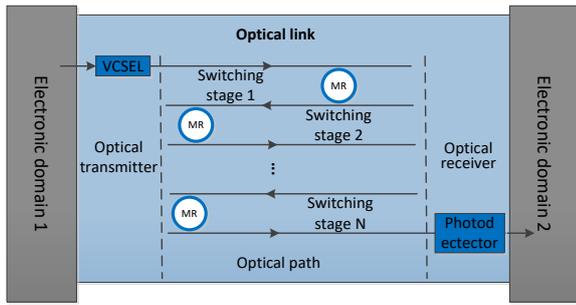


Fig. 3. MRR Switching

B. Thermal Sensitivity of Microring Resonators

For a microring resonator, its resonant wavelength generally depends on the geometric parameters of the microring resonator, as shown in equation (1).

$$\lambda = \frac{n_{eff} \cdot L}{m} \quad (1)$$

Here m is an integer representing the resonant mode, L represents the circumference of the microring resonator and n_{eff} represents the optical modulus-dependent coefficient depending on temperature. n_{eff} has an approximately linear temperature-sensitive characteristic, so the microring wavelength can also be considered to change linearly with temperature. At the same time, the frequency response characteristics of microring resonators are periodic, as shown in Fig. 5.

The distance between adjacent peaks of the continuous resonance curve is called free spectral range of the microring resonator. Different channel wavelengths should be selected within the same FSR(Free Spectral Range). The number of wavelengths used in the interconnection system is n_λ , and the sensitivity of the microring wavelength is k , then allowable temperature gradient within the same FSR is:

$$\Delta T = \frac{FSR}{k \cdot n_\lambda} \quad (2)$$

When the temperature difference of the whole piece or the temperature change exceeds this value, a thermal stability control strategy needs to be introduced to avoid crosstalk between channels. The traditional method is to use a heating ring. When the temperature is reduced and the wavelength is blue shifted, the microring is heated back to the original tuning point. When the temperature is raised and the wavelength is red shifted, the microring is heated through heating. A resonant wavelength in the FSR leads to a larger microring tuning overhead. In this topic, the system level thermal stability control method is adopted to improve the temperature environment of the microring by reasonably guiding and distributing the heat generated by the functional components themselves, thereby a microring tuning scheme with low power consumption is formed.

The temperature variation of the optical node N can be expressed as:

$$\Delta T_N = R_{ek} \cdot \Delta P_k \quad (3)$$

P_k is composed of four parts: P_{core} , P_{comm} , P_{cache} , and P_{heater} , which respectively calculate the power consumption for the processor. The circuit is powered by the unit communication power, cache read/write power consumption and heating

loop tuning power consumption.

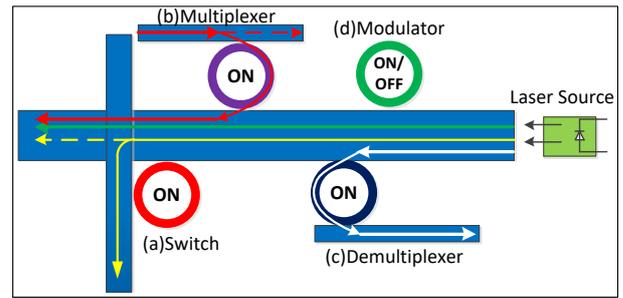


Fig. 4. Representative schematics of ring-resonator building blocks.

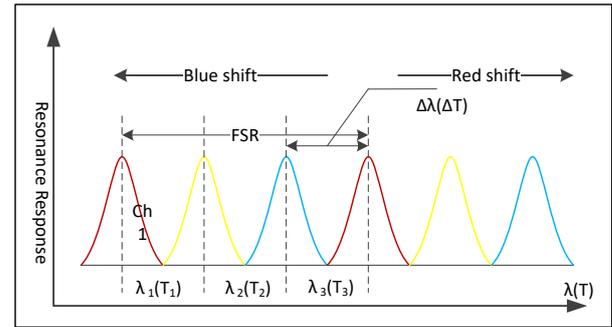


Fig. 5. Resonant wavelength change curve

In view of adjusting communication power consumption of individual routing units, it may lead to route congestion, thus forming bandwidth bottleneck of the entire communication system. This article will no longer use communication power as an adjustment object.

With a rise in temperature, rings will not resonate at the intended frequency. Modulators, switches, multiplexers, and demultiplexers will produce erroneous outputs if thermal shifts are not addressed. Fig. 4 shows several scenarios showing the intended and the actual outputs when a ring fails to resonate at the intended frequency due to a rise in temperature.

C. Microring-aware thermal-balanced task mapping

Considering the thermal balance problem, the background problem of task mapping algorithm design becomes more complex. Constraints of algorithm design include not only resource limitations but also threshold temperature or TDP power constraint caused by thermal effects. The optimization goal is no longer simply to pursue the communication distance, the delay as small as possible, the system throughput is as large as possible. At the same time, optimization of the peak temperature distribution is considered to avoid hot spots and realize heat balance and so on.

Mapping tasks to NoC systems is multiple to multiple mapping problems where each task needs to be determined. The position of processing unit is placed. Different allocation schemes may have different effects on performance indicators, such as energy consumption, fault tolerance and thermal equilibrium.

Before the task runs, the loop aware thermal balance task mapping is implemented first. Let the microring operates at the reference temperature of the tuning frequency as T_0 and temperature difference of the tuning frequency operating in

adjacent FSR is ΔT . When the temperature distribution of the optical node satisfies Equation (4), each microring can work in stable condition.

$$T_N = T_0 \pm k\Delta T \quad (4)$$

Task mapping follows the steps below:

1) Calculate the power consumption P_0 and ΔP corresponding to T_0 and ΔT based on equation (3).

2) Estimate the deviation of calculated power P_i and all tasks, ie:

$$\Delta P_i = P_i - (P_0 \pm k\Delta P) \quad (5)$$

3) The task with smallest power consumption deviation is first mapped to the processor node having same plane coordinates as the optical node. That means d-0 mapping shown in Fig. 6 is completed. After that, d-1 mapping is performed so that the total power consumption deviations of all nodes in the mapping area of each optical node d-1 are approximately equal and tends to 0. the formula is Equation (6).

$$\sum_{k \in M_{1_d1}} \Delta P_k = \sum_{k \in M_{2_d1}} \Delta P_k = \dots = \sum_{k \in M_{L_d1}} \Delta P_k \quad (6)$$

4) By analogy, the light nodes radiate outward until all task mappings are completed.

The task map is shown in Fig. 6. Tasks with the least power consumption from the core map at the bottom of the optical node are scaled out in order until the mapping of all tasks is completed.

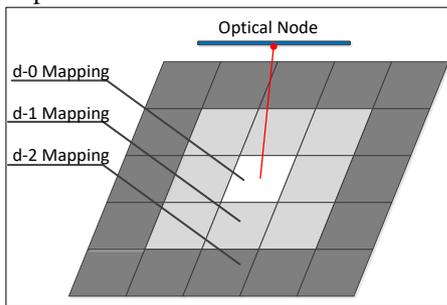


Fig. 6. Mapping distribution

III. SIMULATION RESULTS AND COMPARISONS

Optimized and un-optimized temperature conditions of 3Dmesh topology is evaluated through the mapping algorithm. The cycle precision simulator on account of SystemC is developed for network simulation of optical NoC based on 3D-mesh. Network simulation is carried out in several practical applications including FPPPP, H263E, H264DH, H26DL, ROBOT, SAMPLE and SPARSE. For each application, traffic information is used to simulate the temperature distribution of McPAT chip [21] and HotSpot [22]. The specific simulation process is shown in Fig. 7. Laser wavelength and resonant wavelength of microring resonators are 1550nm at room temperature.

A. The effectiveness of the mapping algorithm

In the initial un-optimized mapping, the original mapping is based on the shortest path to map. The simulated task power consumption is introduced into the HotSpot to generate the temperature situation. Then we remap the task through our optimization algorithm, and we can also get a new temperature condition by performing the above

operation. Ideally, our optimized temperature is better than the one without optimization. Actually as shown in Fig. 8, the task at this time is chosen as the basic task and core steady-state temperature before the algorithm is 324.915K. When the core steady temperature below the light node after our algorithm is changed, the core steady temperature is 322.633K and temperature of core at the bottom of time node has an obvious lower temperature. The proposed optimization algorithm has obvious advantages for the thermal sensing of microring.

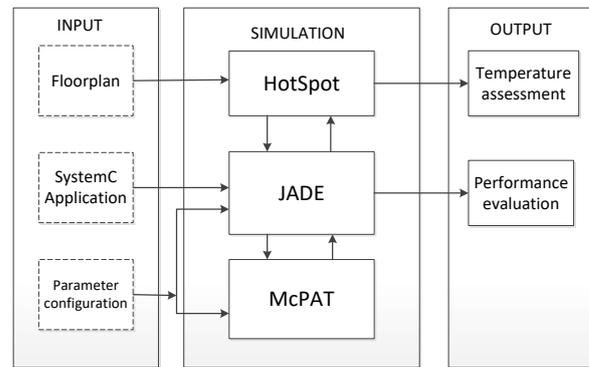


Fig. 7. Simulation flow chart

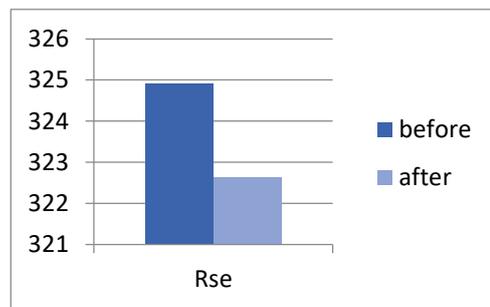


Fig. 8. Rse Simulation result diagram

B. Other task and Network performance

A task with a large number of tasks is selected. The proposed mapping algorithm has much impact on the core temperature below the optical node. The temperature situation is shown in Fig. 9.

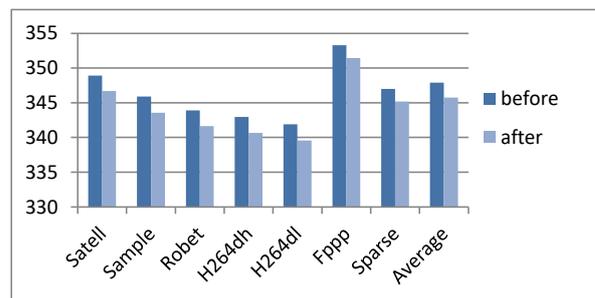


Fig. 9. Multi application simulation result diagram

IV. CONCLUSION

In this work, based on the photo-thermal modeling platform, the thermal effects in optical NoC are modeled from a system level perspective. An off-line task mapping algorithm is proposed based on microring thermal-awareness effects, through observation of temperature before and after the change. The simulation results show that in a $8 \times 8 \times 2$ 3D-mesh optical NoC under a real application workload, after remapping through our proposed mapping algorithm,

core temperature below the optical node is generally reduced by 1K to 2K.

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